

SN54LS348, SN74LS348 (TIM9908) 8-LINE TO 3-LINE PRIORITY ENCODERS WITH 3-STATE OUTPUTS

SDLS161 – OCTOBER 1976 – REVISED MARCH 1988

- 3-State Outputs Drive Bus Lines Directly
- Encodes 8 Data Lines to 3-Line Binary (Octal)
- Applications Include:
N-Bit Encoding
Code Converters and Generators
- Typical Data Delay . . . 15 ns
- Typical Power Dissipation . . . 60 mW

description

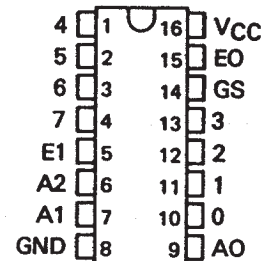
These TTL encoders feature priority decoding of the inputs to ensure that only the highest-order data line is encoded. The 'LS348 circuits encode eight data lines to three-line (4-2-1) binary (octal). Cascading circuitry (enable input E1 and enable output E0) has been provided to allow octal expansion. Outputs A0, A1, and A2 are implemented in three-state logic for easy expansion up to 64 lines without the need for external circuitry. See Typical Application Data.

FUNCTION TABLE

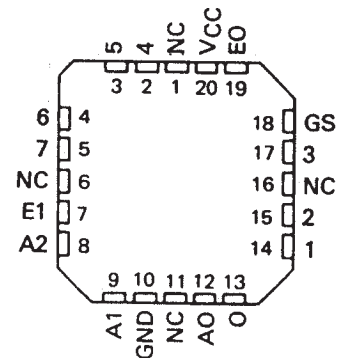
EI	INPUTS								OUTPUTS				
	0	1	2	3	4	5	6	7	A2	A1	A0	GS	EO
H	X	X	X	X	X	X	X	X	Z	Z	Z	H	H
L	H	H	H	H	H	H	H	H	Z	Z	Z	H	L
L	X	X	X	X	X	X	X	L	L	L	L	L	H
L	X	X	X	X	X	L	H	H	L	H	L	L	H
L	X	X	X	X	L	H	H	H	L	H	L	L	H
L	X	X	X	L	H	H	H	H	H	L	L	L	H
L	X	X	L	H	H	H	H	H	H	L	H	L	H
L	X	L	H	H	H	H	H	H	H	H	L	L	H
L	L	H	H	H	H	H	H	H	H	H	H	L	H

H = high logic level, L = low logic level, X = irrelevant
Z = high-impedance state

SN54LS348 . . . J OR W PACKAGE
SN74LS348 . . . D OR N PACKAGE
(TOP VIEW)

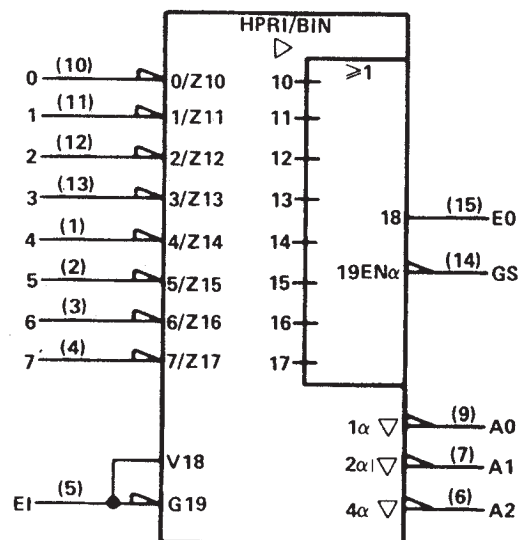


SN54LS348 . . . FK PACKAGE
(TOP VIEW)



NC - No internal connection

logic symbol†



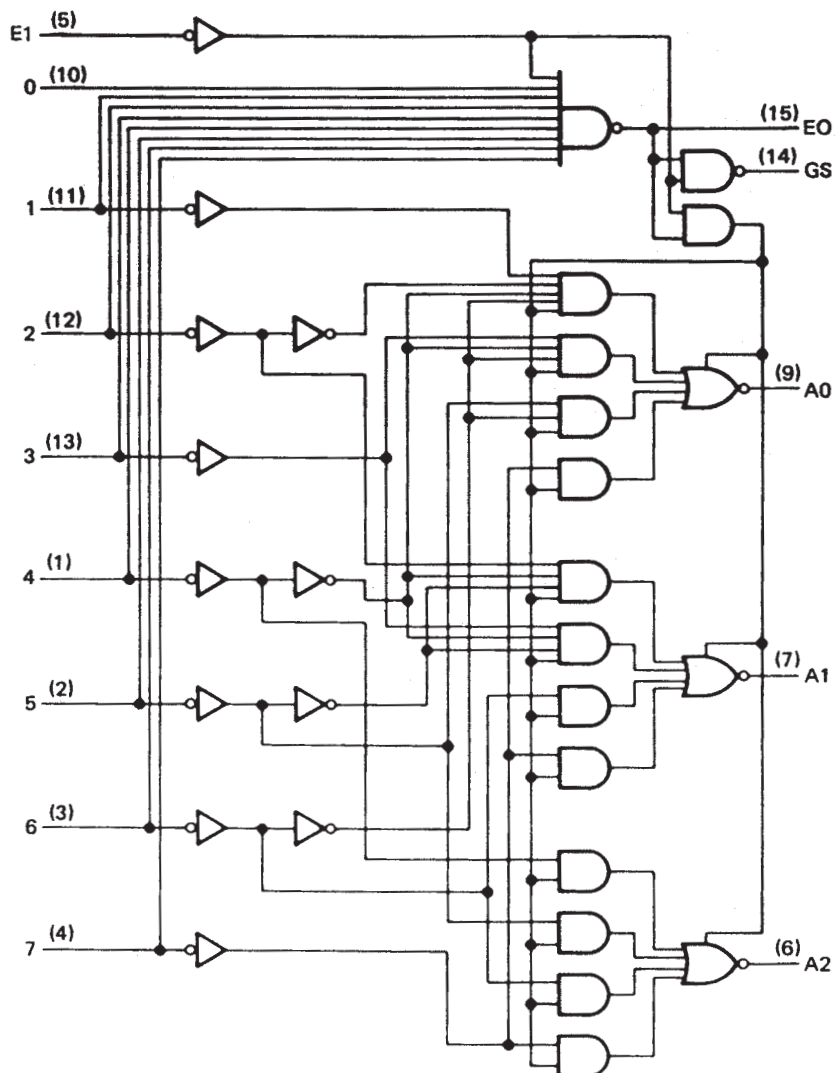
†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

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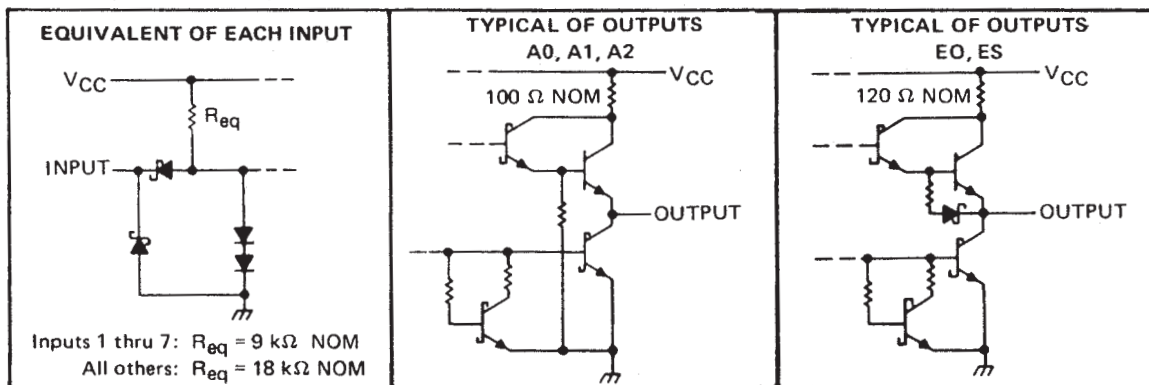
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logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.

schematic of inputs and outputs



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage	7 V
Operating free-air temperature range: SN54LS348	–55°C to 125°C
SN74LS348	0°C to 70°C
Storage temperature range	–65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54LS348			SN74LS348			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}		4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}	A0, A1, A2	–1			–2.6			mA
	EO, GS	–400			–400			μA
Low-level output current, I_{OL}	A0, A1, A2	12			24			mA
	EO, GS	4			8			mA
Operating free-air temperature, T_A		–55	125		0	70		°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS†		SN54LS348		SN74LS348		UNIT
					MIN	TYP‡	MAX	MIN	
V _{IH} High-level input voltage					2		2		V
V _{IL} Low-level input voltage					0.7		0.8		V
V _{IK} Input clamp voltage			V _{CC} = MIN, I _I = −18 mA		−1.5		−1.5		V
V _{OH} High-level output voltage	A0, A1, A2	V _{CC} = MIN, V _{IH} = 2 V,	I _{OH} = −1 mA	2.4	3.1			V	
			I _{OH} = −2.6 mA			2.4	3.1		
	EO, GS	V _{IL} = V _{ILmax}	I _{OH} = −400 μA	2.5	3.4	2.7	3.4		
V _{OL} Low-level Output voltage	A0, A1, A2	V _{CC} = MIN, V _{IH} = 2 V,	I _{OL} = 12 mA	0.25 0.4		0.25 0.4		V	
			I _{OL} = 24 mA			0.35 0.5			
	EO, GS	V _{IL} = V _{ILmax}	I _{OL} = 4 mA	0.25 0.4		0.25 0.4			
			I _{OL} = 8 mA			0.35 0.5			
I _{OZ} Off-State (high-impedance state) output current	A0, A1, A2	V _{CC} = MAX, V _{IH} = 2 V	V _O = 2.7 V	20		20		μA	
			V _O = 0.4 V	−20		−20			
I _I Input current at maximum input voltage	Inputs 1 thru 7	V _{CC} = MAX, V _I = 7 V	0.2		0.2		mA		
	All other inputs		0.1		0.1				
I _{IH} High-level input current	Inputs 1 thru 7	V _{CC} = MAX, V _I = 2.7 V	40		40		μA		
	All other inputs		20		20				
I _{IL} Low-level input current	Inputs 1 thru 7	V _{CC} = MAX, V _I = 0.4 V	−0.8		−0.8		mA		
	All other inputs		−0.4		−0.4				
I _{OS} Short-circuit output current§	Outputs A0, A1, A2	V _{CC} = MAX	−30 −130		−30 −130		mA		
	Outputs EO, GS		−20 −100		−20 −100				
I _{CC} Supply current	V _{CC} = MAX, See Note 2		Condition 1	13 25		13 25		mA	
			Condition 2	12 23		12 23			

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$.

§ Not more than one output should be shorted at a time.

NOTE 2: I_{CC} (condition 1) is measured with inputs 7 and EI grounded, other inputs and outputs open. I_{CC} (condition 2) is measured with all inputs and outputs open.



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switching characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER†	FROM (INPUT)	TO (OUTPUT)	WAVEFORM	TEST CONDITIONS	MIN	TYP	MAX	UNIT
tPLH	1 thru 7	A0, A1, or A2	In-phase output	CL = 45 pF, RL = 667 Ω, See Note 3		11	17	ns
tPHL						20	30	
tPLH	1 thru 7	A0, A1, or A2	Out-of-phase output			23	35	ns
tPHL						23	35	
tPZH	EI	A0, A1, or A2				25	39	ns
tPZL						24	41	
tPLH	0 thru 7	EO	Out-of-phase output	CL = 15 pF RL = 2 kΩ, See Note 3		11	18	ns
tPHL						26	40	
tPLH	0 thru 7	GS	In-phase output			38	55	ns
tPHL						9	21	
tPLH	EI	GS	In-phase output			11	17	ns
tPHL						14	36	
tPLH	EI	EO	In-phase output			17	26	ns
tPHL						25	40	
tPHZ	EI	A0, A1, or A2		CL = 5 pF RL = 667 Ω		18	27	ns
tPLZ						23	35	

† tPLH = propagation delay time, low-to-high-level output
tPHL = propagation delay time, high-to-low-level output
tpZH = output enable time to high level
tpZL = output enable time to low level
tpHZ = output disable time from high level
tpLZ = output disable time from low level
NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

TYPICAL APPLICATION DATA

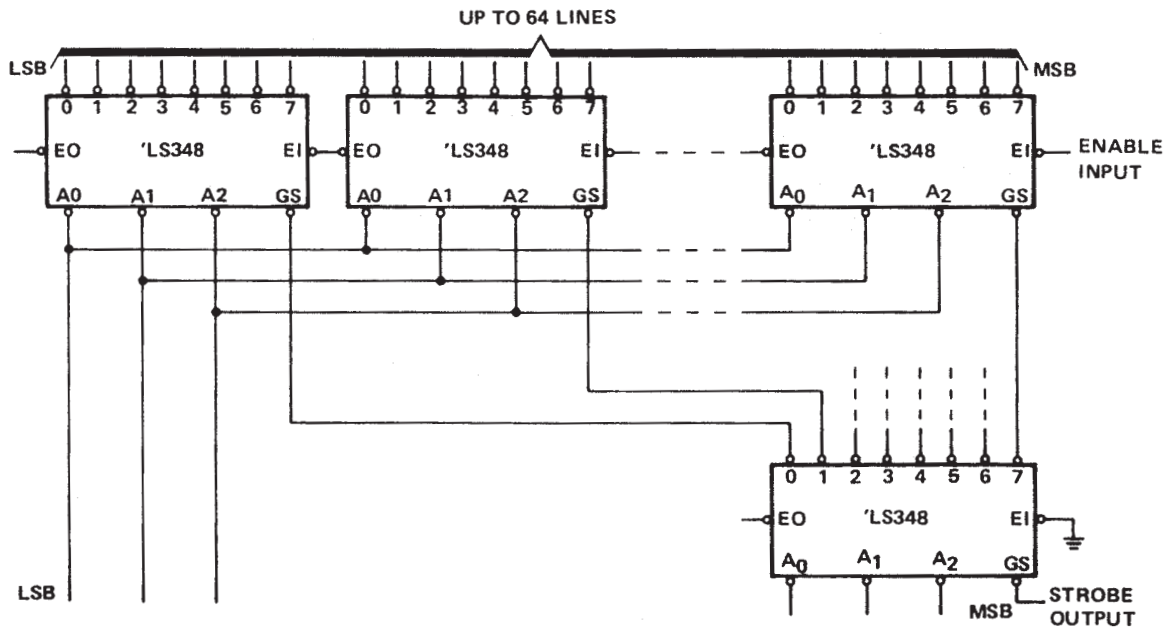


FIGURE 1—PRIORITY ENCODER WITH UP TO 64 INPUTS.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
JM38510/36002B2A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
JM38510/36002BEA	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN54LS348J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN74LS348D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS348N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS348NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54LS348FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54LS348J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SNJ54LS348W	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

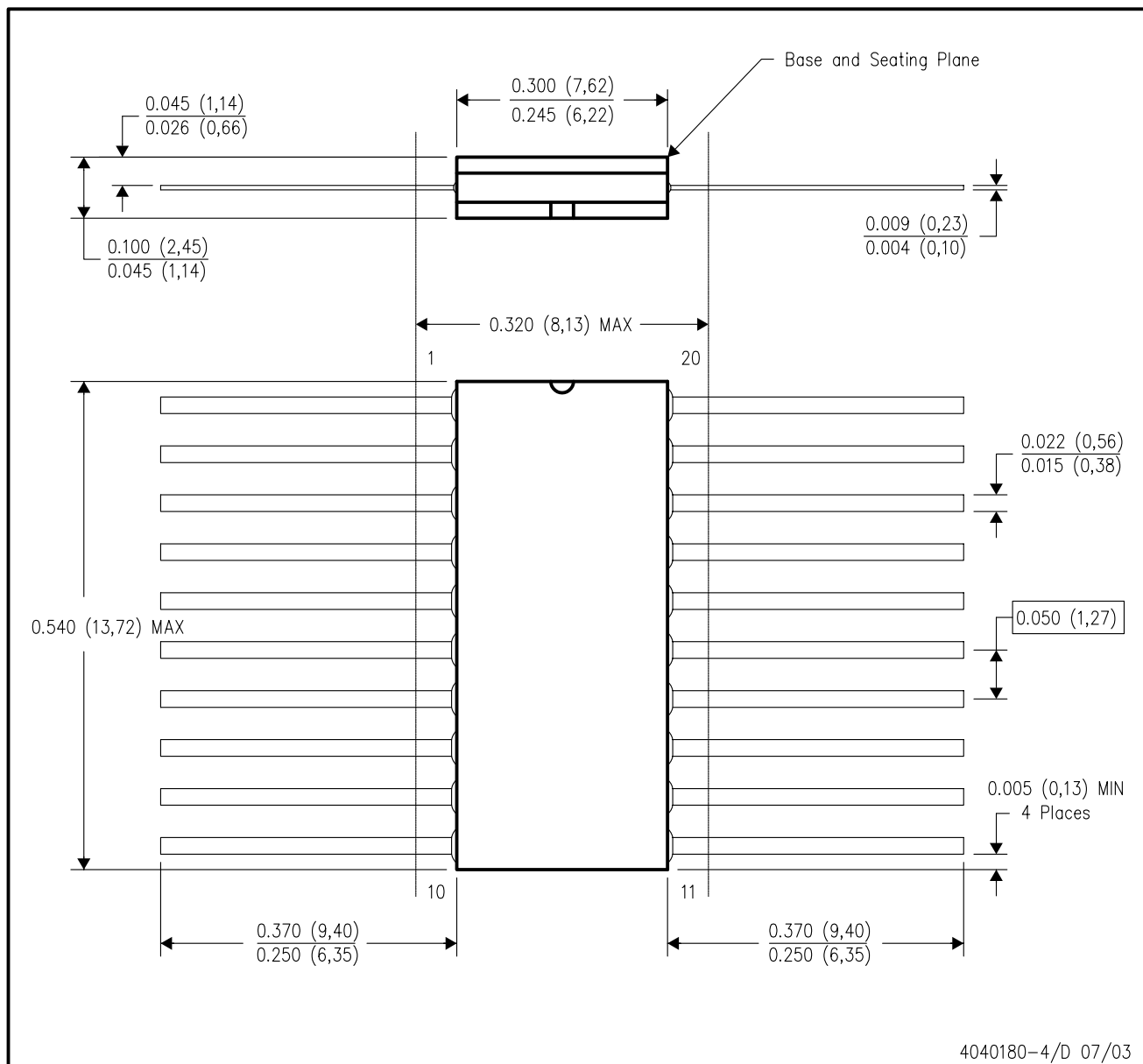


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK

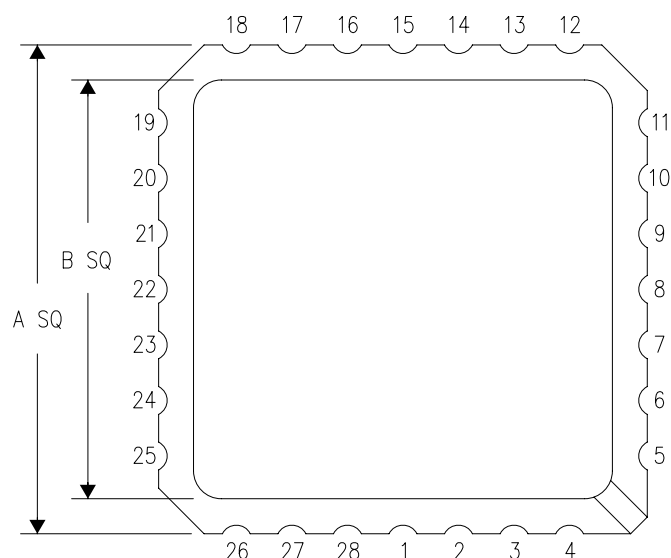


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within Mil-Std 1835 GDFP2-F20

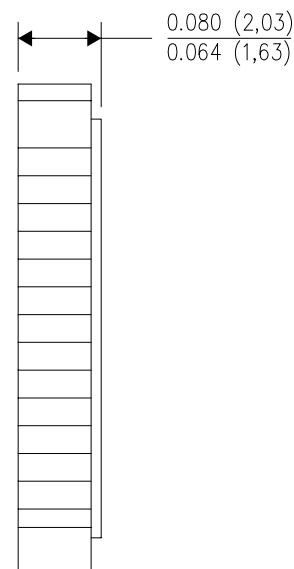
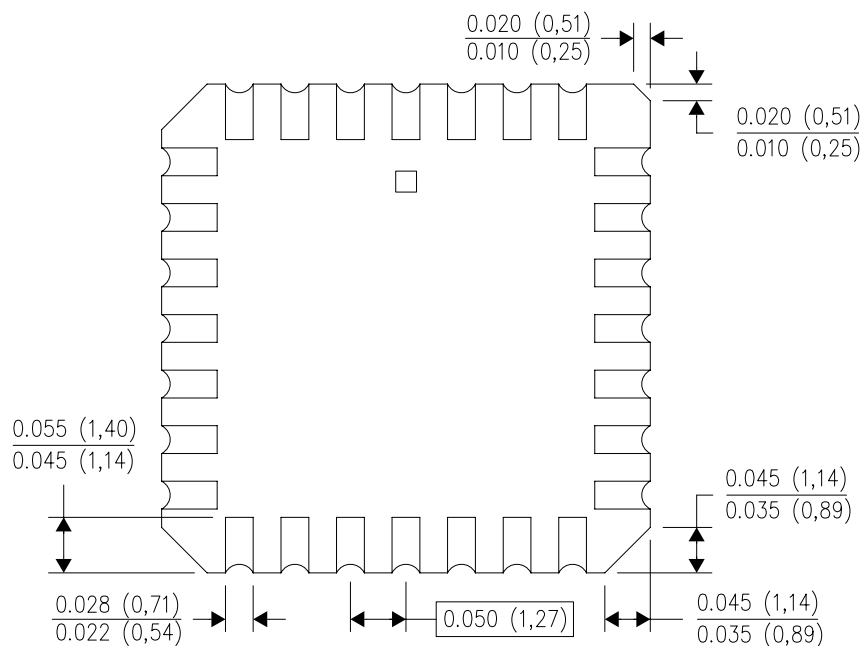
FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD

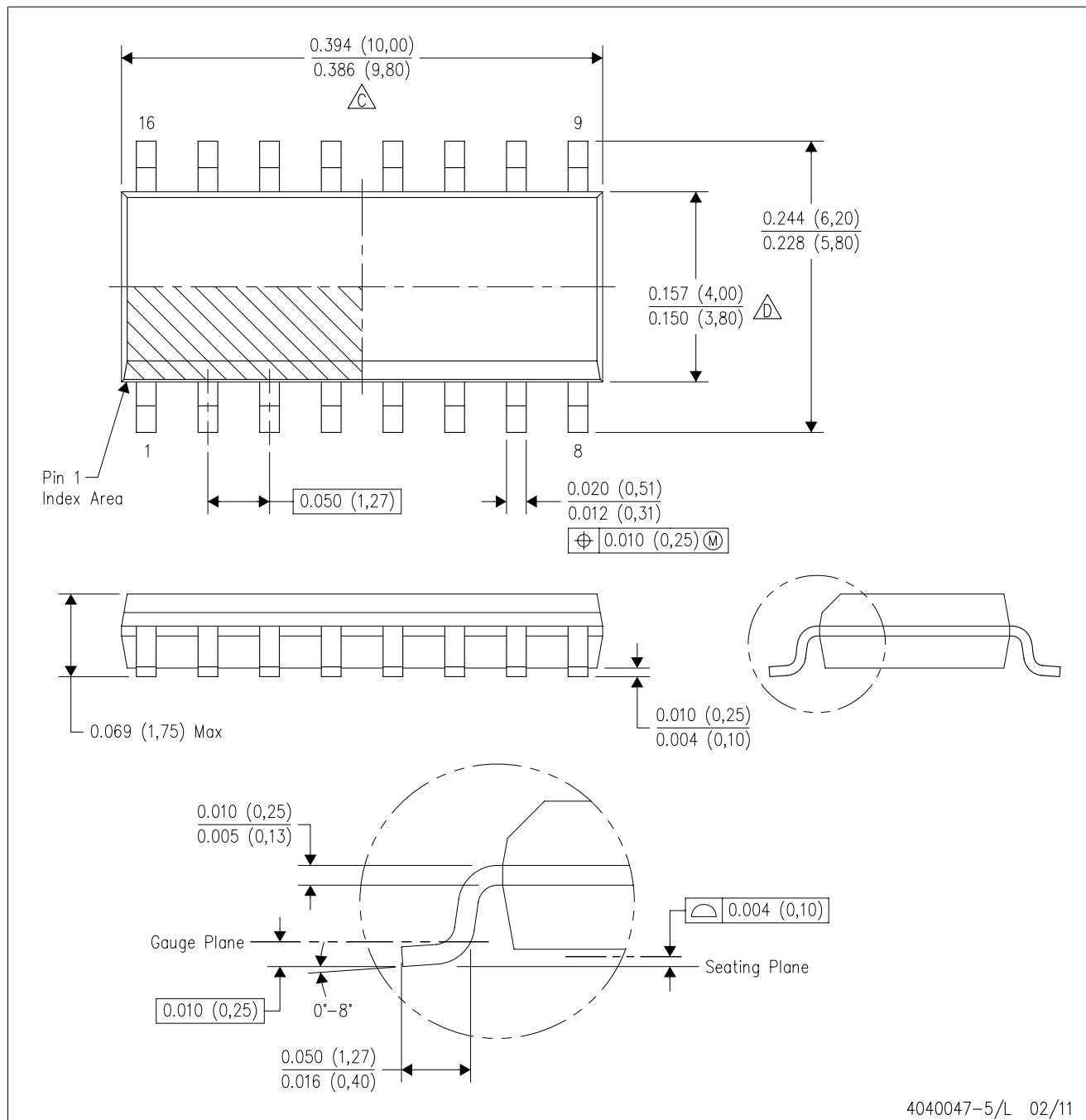


4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - $\triangle D$ The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE

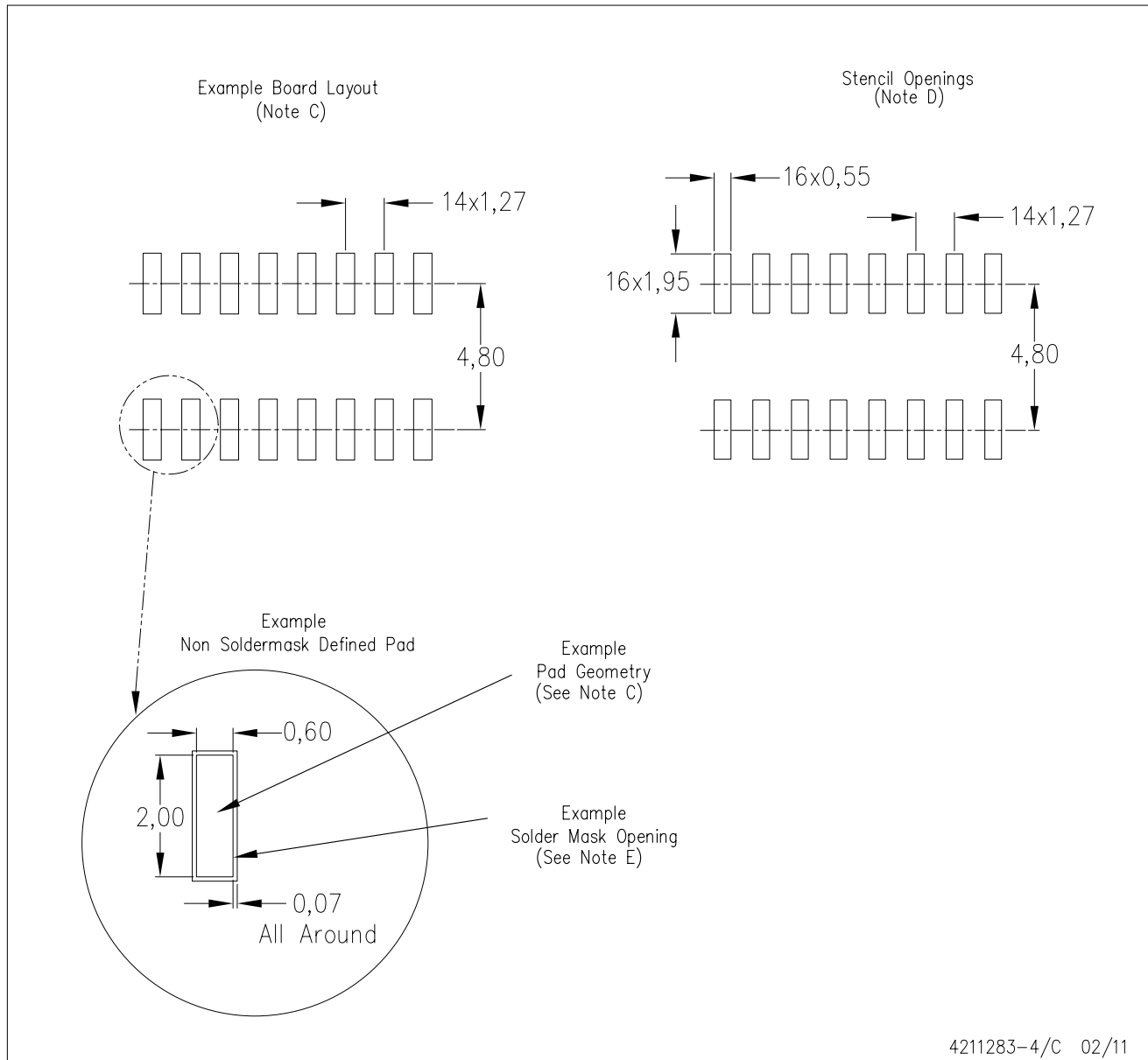


4040047-5/L 02/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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